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FDC610PZ P-Channel PowerTrench[®] MOSFET **–30V, –4.9A, 42m**Ω **Features**

- Max $r_{DS(on)}$ = 42m Ω at V_{GS} = -10V, I_D = -4.9A
- Max $r_{DS(on)}$ = 75m Ω at V_{GS} = -4.5V, I_D = -3.7A
- Low gate charge (17nC typical).
- High performance trench technology for extremely low r_{DS(on)}.
- SuperSOTTM –6 package: small footprint (72% smaller than standard SO-8) low profile (1mm thick).
- RoHS Compliant

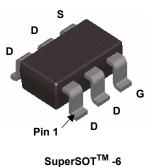


General Description

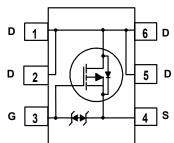
This P-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance. These devices are well suited for battery power applications: load switching and power management, battery charging circuits, and DC/DC conversion.

Application

DC - DC Conversion







MOSFET Maximum Ratings TA= 25°C unless otherwise noted

Symbol	mbol Parameter		Ratings	Units	
V _{DS}	Drain to Source Voltage		-30	V	
V _{GS}	Gate to Source Voltage		±25	V	
1	Drain Current -Continuous	(Note 1a)	-4.9	^	
D	-Pulsed		-20	Α	
D	Power Dissipation (Note 1a)		1.6	14/	
P _D	Power Dissipation	(Note 1b)	0.8	W	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C	

Thermal Characteristics

$R_{ hetaJA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	78	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	156	C/VV

Package Marking and Ordering Information

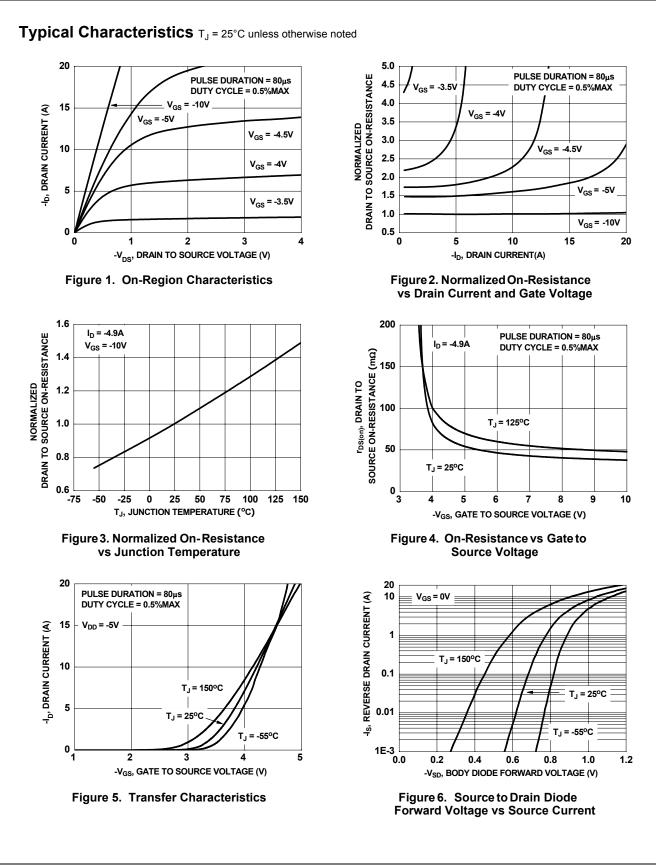
Device Marking	Device	Package	Reel Size	Tape Width	Quantity
.610Z	FDC610PZ	SSOT6	7"	8mm	3000units

August 2007

GaseGate to Source Leakage Current $V_{GS} = \pm 25V$, $V_{DS} = 0V$ ± 10 μA On Characteristics $V_{GS(th)}$ Gate to Source Threshold Voltage Temperature Coefficient $V_{GS} = V_{DS}$, $I_D = -250\mu A$, referenced to $25^{\circ}C$ 6 $mV/^{\rho_1}$ $DS(on)$ Gate to Source On Resistance $V_{GS} = -10V$, $I_D = -4.9A$ 3642 $mV/^{\rho_1}$ $DS(on)$ Static Drain to Source On Resistance $V_{GS} = -10V$, $I_D = -4.9A$ 3642 $mQ/^{\rho_1}$ $PS(on)$ Static Drain to Source On Resistance $V_{GS} = -10V$, $I_D = -4.9A$, $T_J = 125^{\circ}C$ 5060 V_{CS} Forward Transconductance $V_{DD} = -10V$, $I_D = -4.9A$ 15S bynamic Characteristics $V_{DS} = -15V$, $V_{GS} = 0V$, $f = 1MHz$ 7551005 pF C_{SS} Reverse Transfer Capacitance $f = 1MHz$ 13 Ω C_{SS} Gate Resistance $f = 1MHz$ 13 Ω M_{CS} Turn-On Delay Time r $Rise Time$ γ 14ns C_{MS} Total Gate Charge $V_{GS} = 0V$ to $-10V$ $V_{DD} = -15V$, $I_D = -4.9A$ 410ns C_{MS} Total Gate Charge $V_{GS} = 0V$ to $-10V$ $V_{DD} = -15V$, $I_D = -4.9A$ 2.9nC Q_{gd} Total Gate Charge $V_{GS} = 0V$ to $-10V$ $V_{DD} = -15V$, $I_D = -4.9A$ 2.9nC Q_{gd} Gate to Source Gate Charge $V_{GS} = 0V$ to $-10V$ $V_{DD} = -15V$, $I_D = -4.9A$ 2.9nC Q_{gd} Gate to Charge <td< th=""><th>Symbol</th><th>Parameter</th><th>Test Conditions</th><th>Min</th><th>Тур</th><th>Мах</th><th>Units</th></td<>	Symbol	Parameter	Test Conditions	Min	Тур	Мах	Units
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	I _{GSS}	Gate to Source Leakage Current	V_{GS} = ±25V, V_{DS} = 0V			±10	μA
	On Chara	cteristics					
$ \begin{array}{c c c c c c c c c } \hline AT_J & Gate to Source Threshold Voltage Temperature Coefficient & I_D = -250 \mu A, referenced to 25°C & 6 & mV/^{\circ} \\ \hline AT_J & D_D & D_D$			$V_{00} = V_{00}$ $I_0 = -250 \mu \Delta$	_1	_22	_3	V
$\begin{array}{c c c c c c c c c c c c c c c c c c c $				-1	-2.2	-5	
		•	$I_D = -250 \mu A$, referenced to 25°C		6		mV/°C
V _{GS} = -10V, I _D = -4.9A, T _J = 125°C 50 60 HFS Forward Transconductance V _{DD} = -10V, I _D = -4.9A 15 S Dynamic Characteristics Input Capacitance V _{DS} = -15V, V _{GS} = 0V, f = 1MHz 145 195 pF Coss Output Capacitance V _{DS} = -15V, V _{GS} = 0V, f = 1MHz 145 195 pF Crass Reverse Transfer Capacitance f = 1MHz 13 Ω Ω Cost Gate Resistance f = 1MHz 13 Ω Ω Writching Characteristics f = 1MHz 13 Ω Ω d(on) Turn-On Delay Time r V _{DD} = -15V, I _D = -4.9A 4 10 ns r Rise Time Q _{GS} = 0V to -10V V _{GS} = 0V to -10V 33 53 ns Q _g Total Gate Charge V _{GS} = 0V to -4.5V V _{DD} = -4.9A 2.9 nC Q _g Total Gate Charge V _{GS} = 0V to -4.5V V _{DD} = -15V, I _D = -4.9A 2.9 nC Q _g Total Gate Charge V _{GS} = 0V to -4.5V V _{DD} =		· · ·	$V_{GS} = -10V, I_{D} = -4.9A$		36	42	
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Dynamic CharacteristicsCissInput Capacitance $V_{DS} = -15V, V_{GS} = 0V,$ 7551005pFCossOutput Capacitance $f = 1MHz$ 145195pFCrssReverse Transfer Capacitance $f = 1MHz$ 13 Ω CrssReverse Transfer Capacitance $f = 1MHz$ 13 Ω CrssReverse Transfer Capacitance $f = 1MHz$ 13 Ω CrssReverse Transfer Capacitance $f = 1MHz$ 13 Ω RgGate Resistance $f = 1MHz$ 13 Ω Switching Characteristics $V_{DD} = -15V, I_D = -4.9A$ 4 10ns d_{doff} Turn-On Delay Time $V_{GS} = -10V, R_{GEN} = 6\Omega$ 33 53ns f_{af} Fall Time $V_{GS} = 0V \text{ to } -10V$ $V_{DD} = -15V, I_D = -4.9A$ 4 10ns Ω_{g} Total Gate Charge $V_{GS} = 0V \text{ to } -10V$ $V_{DD} = -15V, I_D = -4.9A$ 2.9 nc Ω_{gs} Gate to Source Gate Charge $V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -15V, I_D = -4.9A$ 2.9 nc Ω_{gs} Gate to Drain "Miller" Charge $I_D = -4.9A$ 2.9 nc Ω_{gd} Gate to Drain "Miller" Charge $I_D = -4.9A$ 2.9 ncDrain-Source Diode Characteristics			$V_{GS} = -10V, I_D = -4.9A, T_J = 125^{\circ}C$		50	60	
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Social CrassReverse Transfer CapacitanceT = TMHZ125190pF R_g Gate Resistancef = 1MHz13 Ω Switching Characteristics $d(on)$ Turn-On Delay Time $f = 1MHz$ 13 Ω r_{r} Rise Time $V_{DD} = -15V, I_D = -4.9A$ 4 10ns r_{d} Rise Time $V_{GS} = -10V, R_{GEN} = 6\Omega$ 33 53 ns r_{g} Total Gate Charge $V_{GS} = 0V \text{ to } -10V$ $V_{DD} = -15V, I_D = -4.9A$ 17 24 nC R_{g} Total Gate Charge $V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -15V, I_D = -4.9A$ 17 24 nC R_{g} Total Gate Charge $V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -15V, I_D = -4.9A$ 17 24 nC R_{g} Gate to Source Gate Charge $V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -15V, I_D = -4.9A$ 2.9 nC R_{g} Gate to Drain "Miller" Charge $I_D = -4.9A$ 2.9 nC R_{g} Gate to Drain "Miller" Charge $I_D = -4.9A$ $I_D = -4.9A$ $I_D = -4.9A$ R_{g} Gate to Drain "Miller" Charge $I_D = -4.9A$ $I_D = -4.9A$ $I_D = -4.9A$ R_{g} Gate to Drain "Miller" Charge $I_D = -4.9A$ $I_D = -4.9A$ $I_D = -4.9A$ R_{g} Gate to Drain "Miller" Charge $I_D = -4.9A$ $I_D = -4.9A$ $I_D = -4.9A$ R_{g} $I_D = -4.9A$ $I_D = -4.9A$ $I_D = -4.9A$ $I_D = -4.9A$ R_{g} $I_D = -4.9A$ $I_D = -4.9A$ $I_D = -4.9A$			$V_{DS} = -15V, V_{GS} = 0V,$				
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d(off)Turn-Off Delay Time3353ns f Fall Time2337ns Q_g Total Gate Charge $V_{GS} = 0V \text{ to } -10V$ $V_{DD} = -15V$,1724nC Q_g Total Gate Charge $V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -15V$,913nC Q_{gd} Gate to Source Gate Charge $I_D = -4.9A$ 2.9nC Q_{gd} Gate to Drain "Miller" Charge4.3nCOrain-Source Diode Characteristics	t _r	Rise Time			4	10	ns
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Q _{gd} Gate to Drain "Miller" Charge 4.3 nC Orain-Source Diode Characteristics	Qg	Total Gate Charge			17	24	nC
Q _{gd} Gate to Drain "Miller" Charge 4.3 nC Orain-Source Diode Characteristics	Qg	Total Gate Charge	$V_{GS} = 0V \text{ to } -4.5V V_{DD} = -15V,$		9	13	nC
Drain-Source Diode Characteristics	Q _{gs}	Gate to Source Gate Charge	I _D = -4.9A		2.9		nC
	Q _{gd}	Gate to Drain "Miller" Charge			4.3		nC
	Drain-Sou	urco Diodo Charactoristics					
2 Maximum Continuous Drain-Source Diode Forward Current			de Ferryard Ourreat		1	4.0	•
					0.0		
			$V_{GS} = 0V, I_{S} = -1.5A$ (Note 2)				-
			– I _F = –4.9A, di/dt = 100A/μs				
rr Reverse Recovery Time $I_{\rm E} = -4.9$ A, di/dt = 100A/us 19 35 ns		Reverse Recovery Charge			9	10	lic
	Q _{gs} Q _{gd}	Gate to Source Gate Charge Gate to Drain "Miller" Charge urce Diode Characteristics Maximum Continuous Drain-Source Dic Source to Drain Diode Forward Voltage	bde Forward Current $V_{GS} = 0V, I_S = -1.3A$ (Note 2)		2.9 4.3 -0.8	-1.3 -1.2	
SD contract or brain product or ward voltage $v_{GS} = vv$, $v_{GS} = 1.3A$ (NULE 2) -0.0 -1.2 V	rr		I _E = -4.9A, di/dt = 100A/us				
rr Reverse Recovery Time $I_{\rm E} = -4.9$ A, di/dt = 100A/us 19 35 ns	Q _{rr}	Reverse Recovery Charge			9	18	nC
$\frac{19}{18} = -4.9A, di/dt = 100A/\mu s$. $R_{\theta JA}$ is determ	nined with the device mounted on a 1in ² pad 2 oz coppe	r pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{ m R,IC}$ is	guaranteed I	by design wh	ile R _{0CA} is de	etermined
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	the user's boa	ird design.					
rrReverse Recovery TimeIF = -4.9A, di/dt = 100A/ μ s1935ns Q_{rr} Reverse Recovery Charge918nCotes:00000		a. 78°C/W w	hen mounted on a	b. 156°	C/W when m	ounted on a	
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$\begin{array}{ c c c c c c c c }\hline rr & Reverse Recovery Time & I_F = -4.9A, di/dt = 100A/\mu s & 19 & 35 & ns \\ \hline Q_{rr} & Reverse Recovery Charge & I_F = -4.9A, di/dt = 100A/\mu s & 9 & 18 & nC \\\hline otes: & & & \\ R_{0JA} \text{ is determined with the device mounted on a 1in2 pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0JC} is guaranteed by design while R_{0CA} is determined the user's board design. \hline \end{array}$							
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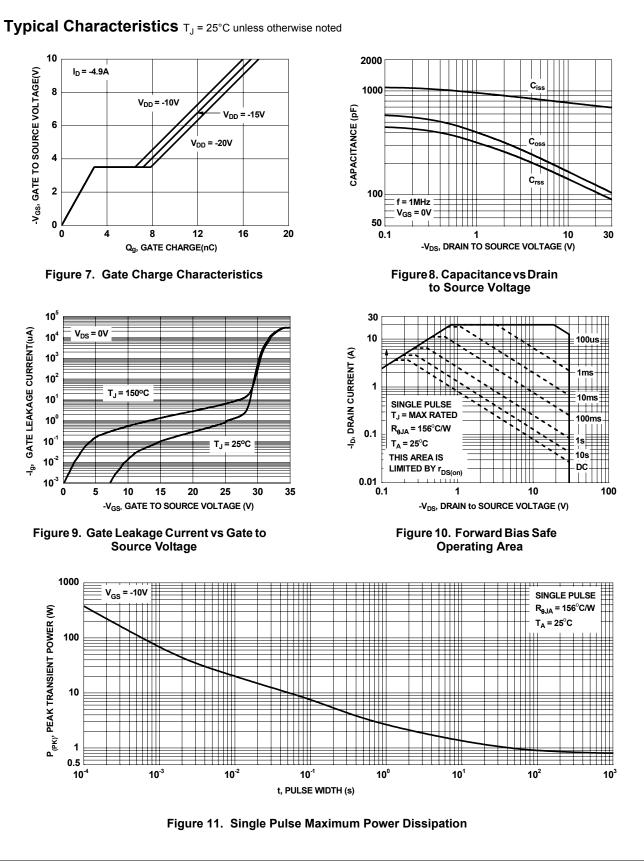
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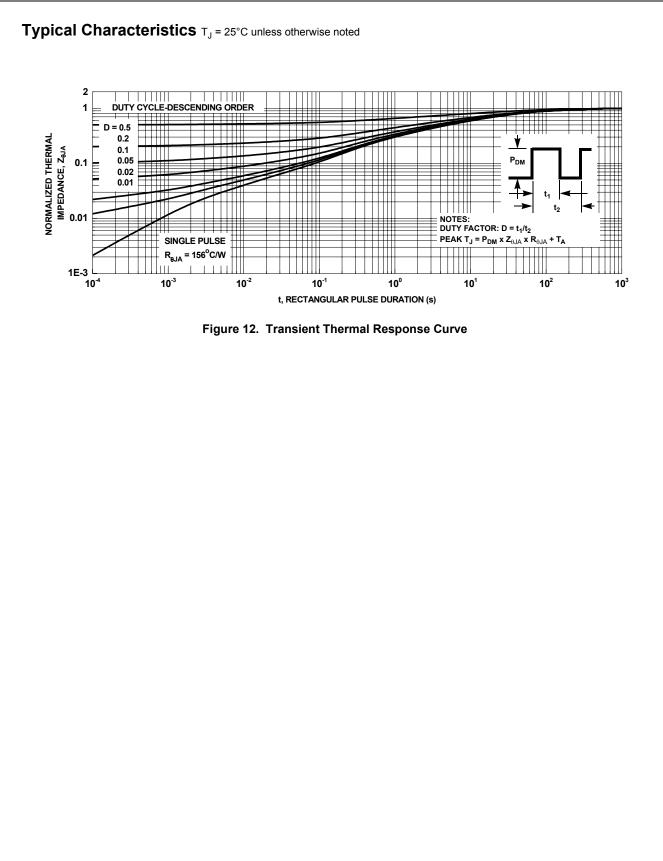
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